As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METALLIZATION STRUCTURES FOR SEMICONDUCTOR DEVICE INTERCONNECTS, METHODS FOR MAKING SAME, AND SEMICONDUCTOR DEVICES INCLUDING SAME, the specification of which (check one):

□ was filed on as □ was filed on as	S United States application serial no	and was amended on and was amended under PCT Article 19 on		
			~ ~~~ '	
I hereby state that I have reviewed referred to above.	ed and understand the contents of the abov	e-identified specification, including the claims, as an	lended by any amendment	
I acknowledge the duty to disclosmatter claimed in this application, as	se to the U.S. Patent and Trademark Offic s "materiality" is defined in Title 37, Code	e all information known to me to be material to the p of Federal Regulations § 1.56.	patentability of the subject	
I haraby claim foreign priority h	enefits under Title 35 United States Code	§ 119(a)-(d) or § 365(b) of any foreign application	(s) for patent or inventor's	
certificate or § 365(a) of any PCT in attached continuation page and have	nternational application(s) designating at le also identified below and on any attached	ast one country other than the United States of Amer continuation page any foreign application for patent United States of America having a filing date before	rica listed below and on any or inventor's certificate or	
which priority is claimed.				
Prior foreign/PCT application(s):			Priority Claimed	
(number)	(cour	try) (day/month/year filed)	Yes No	
(number)	(cour	try) (day/month/year filed)	Yes No	
application is not disclosed in any suluty to disclose to the U.S. Patent as	ch prior application in the manner provide nd Trademark Office all information know	inuation page and, insofar as the subject matter of ed by the first paragraph of Title 35, United States C n to me to be material to patentability as defined in or application and the national or PCT international f	ode, § 112, I acknowledge Title 37, Code of Federal	
(application serial no.)	(filing date)	(status - pending, patente	(status - pending, patented or abandoned)	
(application serial no.)	(filing date)	(status - pending, patente	xd or abandoned)	
I hereby claim the benefit under		any United States provisional application(s) listed be	low:	
I hereby appoint the following Re	egistered Practitioners to prosecute this ap	plication and to transact all business in the Patent and	i Trademark Office connec	
David V. Trask, Reg. No. 22,01 Laurence B. Bond, Reg. No. 30, Allen C. Turner, Reg. No. 33,04 Stephen R. Christian, Reg. No. 3 Paul C. Oestreich, Reg. No. P-4- Kenneth C. Booth, Reg. No. 42, Lia M. Pappas, Reg. No. 34,095	Joseph A. Walkowski, Reg Kent S. Burningham, Reg. Brick G. Power, Reg. No. Devin R. Jensen, Reg. No. Samuel E. Webb, Reg. No.	. No. 28,765 James R. Duzan, Reg. No. 2 No. 30,453 Edgar R. Cataxinos, Reg. N 38,581 Kenneth B. Ludwig, Reg. N P-44,805 Eleanor V. Goodall, Reg. N	28,393 (o. 39,931 (o. 42,814 (o. 35,162	
Address all correspondence to:	Joseph A. Walkowski, telephone no TRASK, BRITT & ROSSA P.O. BOX 2550 Salt Lake City, Utah 84110	. (801) 532-1922.		
and further that these statements wer	e made with the knowledge that willful fa e United States Code and that such willful	true and that all statements made on information and se statements and the like so made are punishable by false statements may jeopardize the validity of the a	y fine or imprisonment, or	
Full name of sole inventor: Salman Inventor's signature	Akram Sahan AX	ram Date August 31	1999	
Residence: Boise, Idaho Citizenship: Pakistan Post Office Address: 1463 E. Rega	tta, Boise, Idaho 83706			